

True  now Powered by Intelligent Platform  
for Smart Factory 

# KY8030-2

Worlds Best Selling True 3D Solder Paste Inspection



Real Time Warp  
Compensation Solution



User-friendly Software



3D Measurement based  
SMT Process Control  
System

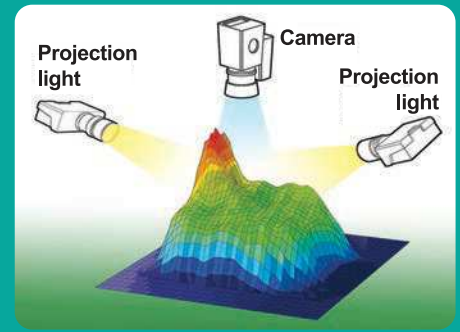


KOH  
YOUNG  
TECHNOLOGY  
INTELLIGENT  
INSPECTION



# KY8030-2

Worlds Best Selling True 3D Solder Paste Inspection



➤ **Dual Projection Technology**  
KY8030-3 delivers true 3D inspection without concern for inaccuracies resulting from shadowing.



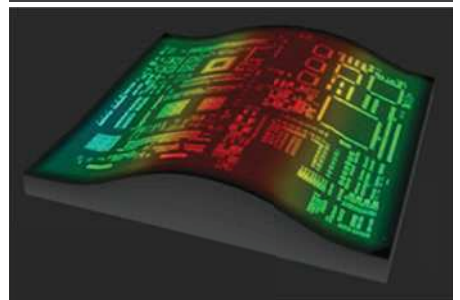
## Warp Compensation Solution

Optional

### ◦ Z-tracking 3D Compensation Solution

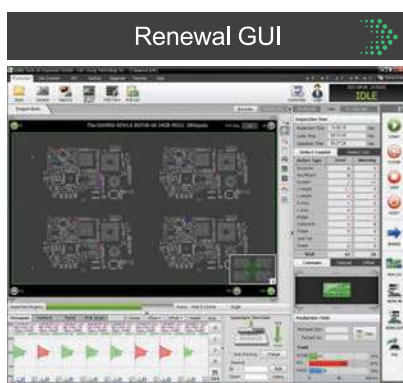
- Koh Young's **Multi-Frequency technology** applied
- Real time measurement and compensation of board warp, with respect to the ideal plane
- Real time online provision of high quality PCB images with measurement data

PCB Warp 3D Display

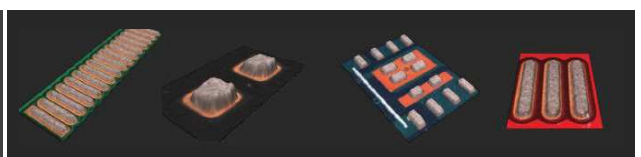


## User-friendly Renewal GUI

- Optimized display for the user with smart menu groupings
- Supports user's defect readability and system usability by more intuitive software
- Detects a wide range of defects using real images and 3D data



Real Color 3D Image  
Optional

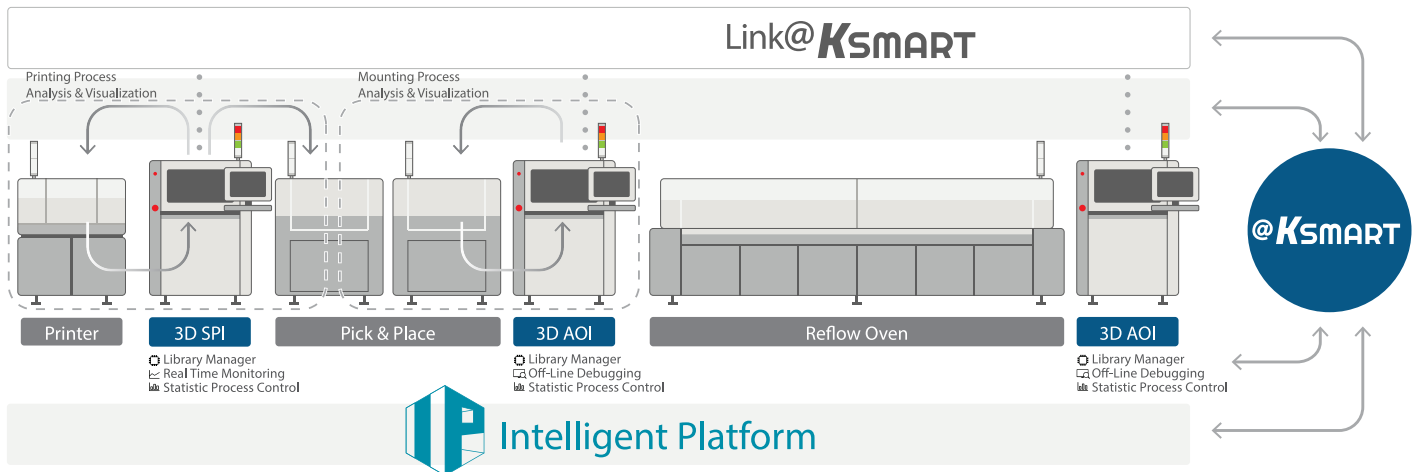


Foreign Material Inspection  
Optional





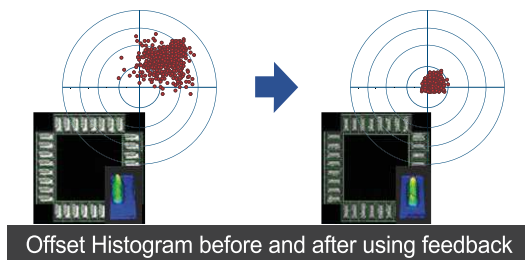
# Intelligent Platform to Realize Fully Automated Process Optimization : Smart Factory



## KSMART Process Optimizer

Optional

- Real time communication of printing process monitoring data with Screen Printers
- Supports pick-and-place process optimization by controlling panels containing defects



Offset Histogram before and after using feedback

- Less Human Intervention
- Live Feedback without Sacrificing Cycle Time



Defect Panel View

- Printing Quality Improvement
- Yield Improvement



## SPC @KSMART

Optional

### Reliable 3D Data based Statistical Process Control

- Carry out essential analyses from an intuitive graphical interface
- Accelerate root cause analysis for increased equipment uptime



SPC Dashboard



Inspection Analysis



## Link @KSMART

Optional

### 3D data based SPI-AOI communication solution

- Review, diagnosis and optimization of printing, pick-and-place and reflow process
- Traces root cause of defects by storing and communicating inspection results from Koh Young's 3D SPI and 3D AOI Systems



3 Point View

# Must-check Requirements of 3D SPI System



Requirements	Solutions																																																								
Solution to Shadow Problem	• 3D Shadow Free Moiré Technology & Dual Projection																																																								
Real time PCB Warp Compensation (2D+3D Solution)	• Warp Compensation																																																								
Operator User-friendliness	• Renewal GUI, Real Color 3D Image																																																								
Foreign Material Inspection	• 3D Foreign Material Inspection (optional)																																																								
Inspection Items	<ul style="list-style-type: none"> <li>• Metrology Capability</li> <li>• Types of Defects</li> </ul>																																																								
Inspection Performance	<table border="1"> <thead> <tr> <th></th> <th>15µm</th> <th>20µm</th> <th>25µm</th> </tr> </thead> <tbody> <tr> <td>Camera Resolution</td> <td>30×30mm(1.18×1.18 inch)</td> <td>40×40mm(1.57×1.57 inch)</td> <td>50×50mm(1.97×1.97 inch)</td> </tr> <tr> <td>FOV Size</td> <td colspan="3">22.5~56.1 cm<sup>2</sup>/sec (Inspection speed varies by PCB and inspection condition.)</td> </tr> <tr> <td>Full 3D Inspection Speed</td> <td>100µm (3.94 mils)</td> <td>150µm (5.91 mils)</td> <td>200µm (7.87 mils)</td> </tr> <tr> <td>Min. Distance between Paste Deposit</td> <td colspan="3"> <ul style="list-style-type: none"> <li>• 4M Pixel Camera</li> <li>• IR-RGB LED Dome Styled Illumination (optional)</li> <li>• 0.37µm</li> <li>• 1µm</li> <li>• &lt; 10% at 6σ</li> </ul> </td> </tr> <tr> <td>Camera</td> <td colspan="3"> <ul style="list-style-type: none"> <li>• 10×10mm</li> <li>• 0.39×0.39 inch</li> </ul> </td> </tr> <tr> <td>Illumination</td> <td colspan="3"> <ul style="list-style-type: none"> <li>• 400µm (2mm optional)</li> <li>• 15.75 mils (78.74 mils optional)</li> </ul> </td> </tr> <tr> <td>Z Resolution</td> <td colspan="3"> <ul style="list-style-type: none"> <li>• 100µm (150µm paste height)</li> <li>• 3.94 mils (5.91 paste height)</li> </ul> </td> </tr> <tr> <td>Height Accuracy (on KY Calibration target)</td> <td colspan="3"> <ul style="list-style-type: none"> <li>• Possible</li> </ul> </td> </tr> <tr> <td>01005 Inspection Capacity Gage R&amp;R (±50% tolerance)</td> <td colspan="3"></td> </tr> <tr> <td>Max. Inspection Size</td> <td colspan="3"></td> </tr> <tr> <td>Max. Inspection Height</td> <td colspan="3"></td> </tr> <tr> <td>Min. Distance between PADs</td> <td colspan="3"></td> </tr> <tr> <td>Various colored PCB Inspection</td> <td colspan="3"></td> </tr> </tbody> </table>		15µm	20µm	25µm	Camera Resolution	30×30mm(1.18×1.18 inch)	40×40mm(1.57×1.57 inch)	50×50mm(1.97×1.97 inch)	FOV Size	22.5~56.1 cm <sup>2</sup> /sec (Inspection speed varies by PCB and inspection condition.)			Full 3D Inspection Speed	100µm (3.94 mils)	150µm (5.91 mils)	200µm (7.87 mils)	Min. Distance between Paste Deposit	<ul style="list-style-type: none"> <li>• 4M Pixel Camera</li> <li>• IR-RGB LED Dome Styled Illumination (optional)</li> <li>• 0.37µm</li> <li>• 1µm</li> <li>• &lt; 10% at 6σ</li> </ul>			Camera	<ul style="list-style-type: none"> <li>• 10×10mm</li> <li>• 0.39×0.39 inch</li> </ul>			Illumination	<ul style="list-style-type: none"> <li>• 400µm (2mm optional)</li> <li>• 15.75 mils (78.74 mils optional)</li> </ul>			Z Resolution	<ul style="list-style-type: none"> <li>• 100µm (150µm paste height)</li> <li>• 3.94 mils (5.91 paste height)</li> </ul>			Height Accuracy (on KY Calibration target)	<ul style="list-style-type: none"> <li>• Possible</li> </ul>			01005 Inspection Capacity Gage R&R (±50% tolerance)				Max. Inspection Size				Max. Inspection Height				Min. Distance between PADs				Various colored PCB Inspection			
	15µm	20µm	25µm																																																						
Camera Resolution	30×30mm(1.18×1.18 inch)	40×40mm(1.57×1.57 inch)	50×50mm(1.97×1.97 inch)																																																						
FOV Size	22.5~56.1 cm <sup>2</sup> /sec (Inspection speed varies by PCB and inspection condition.)																																																								
Full 3D Inspection Speed	100µm (3.94 mils)	150µm (5.91 mils)	200µm (7.87 mils)																																																						
Min. Distance between Paste Deposit	<ul style="list-style-type: none"> <li>• 4M Pixel Camera</li> <li>• IR-RGB LED Dome Styled Illumination (optional)</li> <li>• 0.37µm</li> <li>• 1µm</li> <li>• &lt; 10% at 6σ</li> </ul>																																																								
Camera	<ul style="list-style-type: none"> <li>• 10×10mm</li> <li>• 0.39×0.39 inch</li> </ul>																																																								
Illumination	<ul style="list-style-type: none"> <li>• 400µm (2mm optional)</li> <li>• 15.75 mils (78.74 mils optional)</li> </ul>																																																								
Z Resolution	<ul style="list-style-type: none"> <li>• 100µm (150µm paste height)</li> <li>• 3.94 mils (5.91 paste height)</li> </ul>																																																								
Height Accuracy (on KY Calibration target)	<ul style="list-style-type: none"> <li>• Possible</li> </ul>																																																								
01005 Inspection Capacity Gage R&R (±50% tolerance)																																																									
Max. Inspection Size																																																									
Max. Inspection Height																																																									
Min. Distance between PADs																																																									
Various colored PCB Inspection																																																									
PCB Handling	<ul style="list-style-type: none"> <li>• Conveyor Width Adjustment</li> <li>• Conveyor Fix Type</li> </ul>																																																								
Software	<ul style="list-style-type: none"> <li>• Supported Input Format</li> <li>• Programming S/W</li> <li>• Statistical Process Control Tool</li> <li>• Operator User-friendliness</li> <li>• Operating System</li> </ul>																																																								
Add-on Solutions	<ul style="list-style-type: none"> <li>• 1D &amp; 2D Handy Barcode Reader</li> <li>• 1D &amp; 2D Inline Barcode Reader</li> <li>• Offline Programming Station</li> <li>• Offline SPC Plus Station</li> <li>• Standard Calibration Target</li> <li>• UPS</li> <li>• Remote Monitoring System</li> <li>• Warp Compensation (Z-tracking)</li> <li>• Foreign Material Inspection</li> <li>• Review Station</li> <li>• KSMART Process Optimizer</li> <li>• IR-RGB Light</li> <li>• Link@KSMART</li> <li>• SPC@KSMART</li> </ul>																																																								

※ Above specifications are subject to change without notice.

	M	L	DL	XL
Max. PCB Size	330×330mm (13×13 inch)	510×510mm (20×20 inch)	Dual: 510×320mm (20×12.6 inch) Single: 510×580mm (20×22.8 inch)	850×690mm (33.4×27.1 inch)
Min. PCB Size	50×50mm (1.97×1.97 inch)			70×70mm (2.7×2.7 inch)
PCB Thickness	0.4~5mm (0.015~0.20 inch)			0.5~8mm (0.02~0.31 inch)
Max. PCB Weight	Standard: 2kg(4.4 lbs), Heavy Weight Option: 5kg(11 lbs)			10kg(22 lbs)
Machine Weight	550kg(1212 lbs)	600kg(1322 lbs)	700kg(1543 lbs)	850kg(1874 lbs)
Bottom Side Clearance	50mm(1.97 inch)			
Supplies	200~240VAC, 50/60Hz Single Phase, 5Kgf/cm <sup>2</sup>			
W	820mm(32.2 inch)	1000mm(39.3 inch)	1350mm(53.1 inch)	
D	1295mm(50.9 inch)	1295mm(50.9 inch)	1475mm(58.0 inch)	1475mm(58.0 inch)
H	1727mm(67.9 inch)			
F	985mm(38.7 inch)		1165mm(45.8 inch)	

